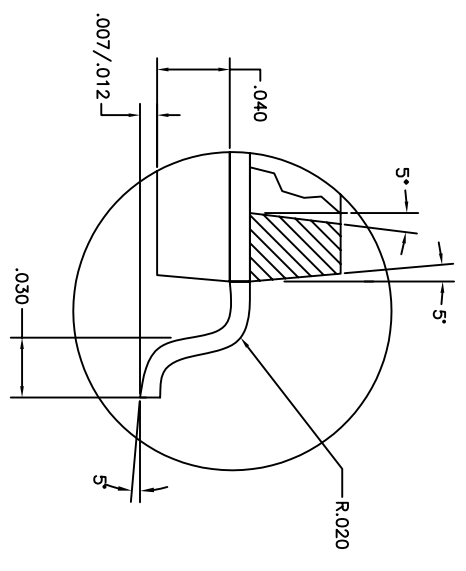
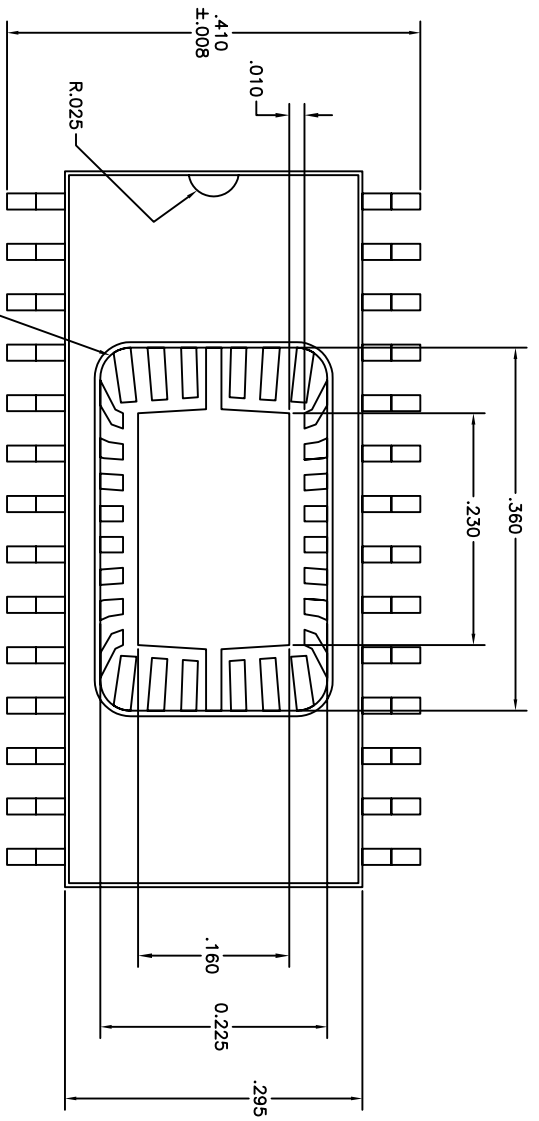


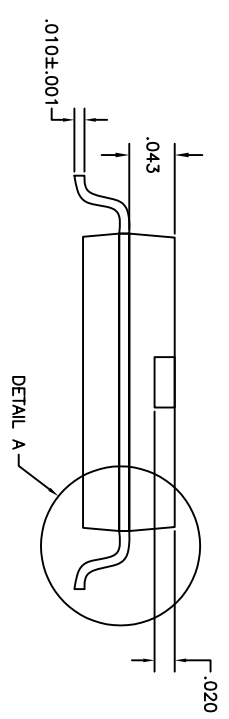
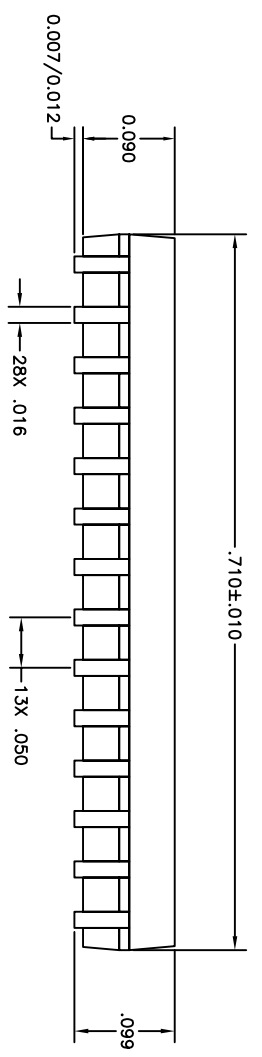
2

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REVISIONS		APPROVED
ECON NO.	DATE	DESCRIPTION
10517	11/3/05	PRODUCTION RELEASE
		D.BENANDIO



DETAIL A
SCALE: 2/1



DETAIL A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEADFRAME: COPPER, FH 194.
 3. LEAD FINISH: FULL AU PLATE.
 4. DIE PAD: .230" x .160".



UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES ARE:
XXX ± 0.01 X.XXXX ± ---
XXXX ± 0.005 ANGLES: ± 1'

DO NOT SCALE DRAWING

DRAWN BY W. GRIFFITTS	DATE 11/2/05
APP BY P. FLASKERUD	DATE 11/2/05
CUSTOMER ---	

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28 Lead 300 mils
SOIC Open-Pak

SIZE A	PART NO. SOIC300-28-0P-01	REV 3
SCALE NONE	FILE SOIC300-28-0P-01-R3.DWG	SHEET 1 OF 1

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